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U.S. Application Serial No. 10/758,827

Atty. Docket No. AM-5852,D1



INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use several sheets if necessary)

Scott Fuller et al.
Applicants

January 15, 2004 Filing Date

<u>1756</u> Group

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Examiner Initial	Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate
NB	4,102,683	07/25/78	DiPiazza	96	38.4	** V** Chronium
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	5,234,990	08/10/93	Flaim et al. *	524	609	
	5,278,010	01/11/94	Day et al.	430	18	
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\prod	5,935,768	08/10/99	Biche et al. **	430	401	
	5,939,236	08/17/99	Pavelchek et al.	430	273.1	
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Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

^{*} Cited in a Search Report in corresponding PCT Application No. PCT/US02/22609.

^{**} Cited during the prosecution of the parent application, U.S. Application Serial No. 09/912,116.

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+	JP 10048832	02/20/98	Sony Corp.	G03F	007/11	Abstract
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<u>m</u>	WO 0054105	09/14/00	Foster et al.	G03C	1/492	

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